CLAIMS

WHAT IS CLAIMED IS:

1. A scribing apparatus, comprising:

a first stage adapted to receive a first substrate,

a second stage adapted to receive a second substrate, and

one or more lasers adapted to emit a laser beam towards the first stage and the second stage and adapted to scribe the substrates.

2. The scribing apparatus of claim 1, wherein the first stage and the second ~~state~~ stage are arranged in a side-by-side orientation.

3. The scribing apparatus of claim 1, wherein the first stage and the second stage comprise rotary stages.

4. The scribing apparatus of claim 1, wherein the first and second stages comprise side-by-side R-Theta stages configured to rotate the first and second substrates in Theta and translate the first and second substrates in R.

5. The scribing apparatus of claim 1, wherein the one or more lasers comprise two lasers whose laser beams are combined to form a scribing laser beam.

10. A method of processing a substrate within an electronic device processing system, comprising:

providing a dual-stage scribing apparatus having a first stage adapted to receive a first substrate, a second stage adapted to receive a second substrate, and one or more lasers adapted to scribe the first substrate and the second substrate;

positioning the first stage at a first location to carry out an orientation process on the first substrate; and

positioning the second stage at a second location to carry out laser scribing of the second substrate as the first substrate is undergoing the orientation process.

11. The method of processing a substrate of claim 10, comprising:

cutting a die attached film with a scribing beam of the dual-stage scribing apparatus.

12. The method of processing a substrate of claim 10, comprising applying a coating on the first substrate and second substrate within a coating apparatus coupled to ~~the~~ a factory interface.

13. A method of processing a singulated substrate, comprising:

providing a singulated substrate having a die attached film;

loading the singulated substrate on a stage of a scribing apparatus; and

cutting the die attached film with a scribing beam of the scribing apparatus.

14. The method of processing a singulated substrate of claim 13, wherein the cutting comprises:

combining two laser beams at a beam delivery head to form the scribing beam.

15. A scribing apparatus, comprising:

a stage adapted to receive a substrate;

a beam delivery head adapted to produce a scribing beam;

a first laser adapted to emit a first laser beam towards the beam delivery head; and

a second laser adapted to emit a second laser beam towards the beam delivery head

wherein the first laser beam and second laser beam are combined within the beam delivery head and produce the scribing beam.